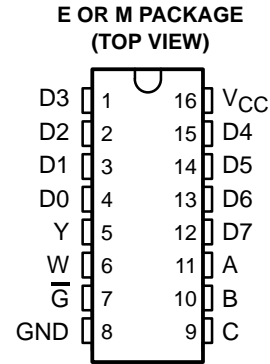


CD74AC151 8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

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- **AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage**
- **8-Line to 1-Line Multiplexers Can Perform as:**
 - Boolean Function Generators
 - Parallel-to-Serial Converters
 - Data Source Selectors
- **Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption**
- **Balanced Propagation Delays**
- **±24-mA Output Drive Current**
 - Fanout to 15 F Devices
- **SCR-Latchup-Resistant CMOS Process and Circuit Design**
- **Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015**



description/ordering information

This data selector/multiplexer provides full binary decoding to select one of eight data sources. The strobe (\overline{G}) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	PDIP – E	Tube	CD74AC151E	CD74AC151E
	SOIC – M	Tape and reel	CD74AC151M96	AC151M

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS				OUTPUTS	
SELECT			STROBE \overline{G}	Y	W
C	B	A			
X	X	X	H	L	H
L	L	L	L	D0	$\overline{D0}$
L	L	H	L	D1	$\overline{D1}$
L	H	L	L	D2	$\overline{D2}$
L	H	H	L	D3	$\overline{D3}$
H	L	L	L	D4	$\overline{D4}$
H	L	H	L	D5	$\overline{D5}$
H	H	L	L	D6	$\overline{D6}$
H	H	H	L	D7	$\overline{D7}$

D0, D1 . . . D7 = the level of the respective D input



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

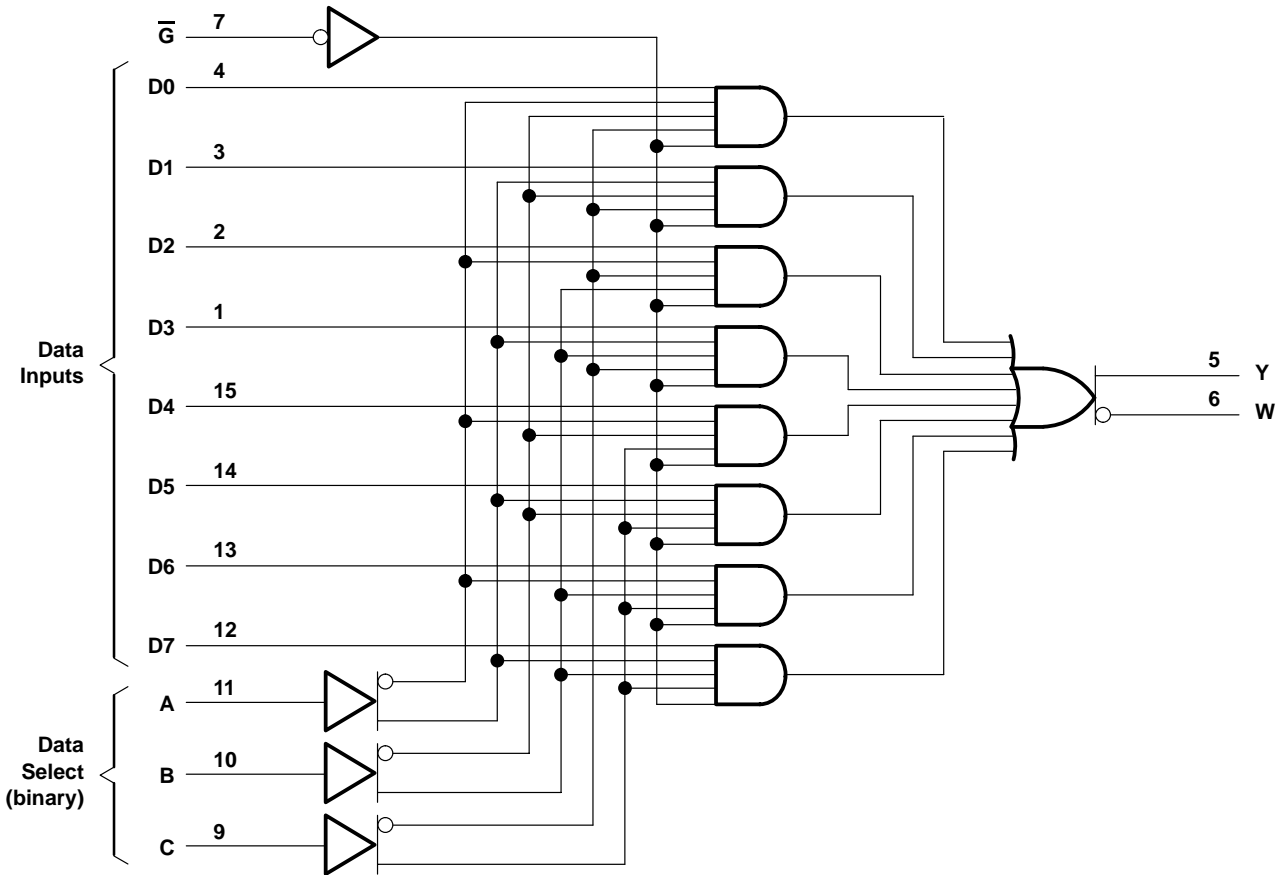
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CD74AC151 8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V_{CC} or GND	± 100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

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recommended operating conditions (see Note 3)

		T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX		
V _{CC}	Supply voltage	1.5	5.5	1.5	5.5	1.5	5.5	V	
V _{IH}	High-level input voltage	V _{CC} = 1.5 V	1.2		1.2		1.2	V	
		V _{CC} = 3 V	2.1		2.1		2.1		
		V _{CC} = 5.5 V	3.85		3.85		3.85		
V _{IL}	Low-level input voltage	V _{CC} = 1.5 V		0.3		0.3		V	
		V _{CC} = 3 V		0.9		0.9			
		V _{CC} = 5.5 V		1.65		1.65			1.65
V _I	Input voltage	0	V _{CC}	0	V _{CC}	0	V _{CC}	V	
V _O	Output voltage	0	V _{CC}	0	V _{CC}	0	V _{CC}	V	
I _{OH}	High-level output current	V _{CC} = 4.5 V to 5.5 V		–24		–24		–24	mA
I _{OL}	Low-level output current	V _{CC} = 4.5 V to 5.5 V		24		24		24	mA
Δt/Δv	Input transition rise or fall rate	V _{CC} = 1.5 V to 3 V		50		50		50	ns/V
		V _{CC} = 3.6 V to 5.5 V		20		20		20	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = –50 μA	1.5 V	1.4		1.4		1.4	V	
			3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
		I _{OH} = –4 mA	3 V	2.58		2.4		2.48		
		I _{OH} = –24 mA	4.5 V	3.94		3.7		3.8		
		I _{OH} = –50 mA [†]	5.5 V			3.85				
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 50 μA	1.5 V		0.1		0.1		V	
			3 V		0.1		0.1			0.1
			4.5 V		0.1		0.1			0.1
		I _{OL} = 12 mA	3 V		0.36		0.5			0.44
		I _{OL} = 24 mA	4.5 V		0.36		0.5			0.44
		I _{OL} = 50 mA [†]	5.5 V				1.65			–
I _I	V _I = V _{CC} or GND	5.5 V		±0.1		±1		±1	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		8		160		80	μA	
C _i				10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 1.5\text{ V}$, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t _{PLH}	D	Y	169		152		ns
t _{PHL}			169		152		
t _{PLH}	D	W	186		169		ns
t _{PHL}			186		169		
t _{PLH}	A, B, or C	Y	228		207		ns
t _{PHL}			228		207		
t _{PLH}	A, B, or C	W	245		223		ns
t _{PHL}			245		223		
t _{PLH}	\bar{G}	Y	153		139		ns
t _{PHL}			153		139		
t _{PLH}	\bar{G}	W	169		153		ns
t _{PHL}			169		153		

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	-55°C to 125°C		-40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t _{PLH}	D	Y	4.7	18.9	4.9	17.1	ns
t _{PHL}			4.7	18.9	4.9	17.1	
t _{PLH}	D	W	5.2	20.9	5.4	19	ns
t _{PHL}			5.2	20.9	5.4	19	
t _{PLH}	A, B, or C	Y	6.4	25.5	6.6	23.2	ns
t _{PHL}			6.4	25.5	6.6	23.2	
t _{PLH}	A, B, or C	W	6.9	27.4	7.1	24.9	ns
t _{PHL}			6.9	27.4	7.1	24.9	
t _{PLH}	\bar{G}	Y	4.3	17.1	4.4	15.5	ns
t _{PHL}			4.3	17.1	4.4	15.5	
t _{PLH}	\bar{G}	W	4.7	18.9	4.9	17.2	ns
t _{PHL}			4.7	18.9	4.9	17.2	



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8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	
t _{PLH}	D	Y	3.4	13.5	3.5	12.3	ns
t _{PHL}			3.4	13.5	3.5	12.3	
t _{PLH}	D	W	3.7	14.9	3.8	13.5	ns
t _{PHL}			3.7	14.9	3.8	13.5	
t _{PLH}	A, B, or C	Y	4.6	18.2	4.7	16.5	ns
t _{PHL}			4.6	18.2	4.7	16.5	
t _{PLH}	A, B, or C	W	4.9	19.6	5.1	17.8	ns
t _{PHL}			4.9	19.6	5.1	17.8	
t _{PLH}	\overline{G}	Y	3.1	12.2	3.1	11.1	ns
t _{PHL}			3.1	12.2	3.1	11.1	
t _{PLH}	\overline{G}	W	3.4	13.5	3.5	12.3	ns
t _{PHL}			3.4	13.5	3.5	12.3	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TYP	UNIT
C _{pd}	Power dissipation capacitance	120	pF

CD74AC151 8-LINE TO 1-LINE DATA SELECTOR/MULTIPLEXER

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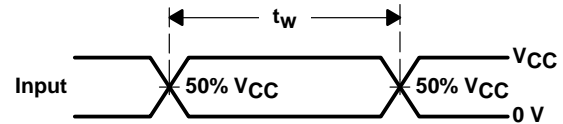
PARAMETER MEASUREMENT INFORMATION



† When $V_{CC} = 1.5 \text{ V}$, $R_1 = R_2 = 1 \text{ k}\Omega$

LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$. Phase relationships between waveforms are arbitrary.
 - For clock inputs, f_{max} is measured with the input duty cycle at 50%.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74AC151E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC151EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC151M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC151M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC151M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC151M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC151M96	SOIC	D	16	2500	333.2	345.9	28.6

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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